

Call for Abstracts - Submit Yours Today!



ASME 2023 INTERPACK[®]

International Technical Conference and Exhibition on
Packaging and Integration of Electronic and Photonic
Microsystems

Location: DoubleTree by Hilton Hotel San Diego Mission Valley, CA
Date: Oct. 24-26, 2023

GO TO: <https://interpack.secure-platform.com/a>

Since 1992, InterPACK has been a premier international conference for the exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics and photonics packaging and heterogeneously integrated systems. InterPACK is a flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The international nature of InterPACK has been highly beneficial in promoting synergy between industry, government, and academia. In addition to technical presentations and exhibitions, InterPACK 2023 will include plenary talks, panel discussions, tutorials, workshops, and an interactive presentation session held along with a career networking event.

Confirmed Plenary Speakers:

Peter de Bock, Program Director, Advanced Research Projects Agency-Energy
Chris Malone, Principal Architect, Meta
Yogendra Joshi, Program Manager, Defense Advanced Research Projects Agency
Waguih Ishak, Division VP and Chief Technologist, Corning
Sumanta Acharya, Program Director, National Science Foundation
Cheolmin Park, Corporate VP, Samsung Electronics

Abstracts (400-650 words) for original papers are solicited in the following general areas of interest with an emphasis on (but not limited to) thermal management and reliability studies.

Technical Tracks:

Heterogeneous Integration	Data Centers and Modular Edge Systems
Electronics Packaging	Power/RF Electronics and Photonics
Multiscale Thermal Transport and Energy Storage	Flexible, Wearable, and Printed Electronics
Transportation Systems, AI and Machine Learning	Interactive Presentations

Publication Schedule

Abstract Submissions Deadline	February 27, 2023
Abstract Acceptance	March 13, 2023
Submission of Draft Paper	May 15, 2023
Submission of Revised Paper	June 19, 2023
Final Paper Submission	July 17, 2023

More information about ASME InterPACK, please visit: <http://event.asme.org/interpack>